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U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10024892	FILING DATE 12/18/2001	CLASS 438	SUBCLASS 2812	GAU 2812	EXAMINER
<b>**APPLICANTS:</b> Kim Jong;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> REPUBLIC OF KOREA 2001-47459 08/07/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials				CU-2641 VE	
TITLE : Method of fabricating a wafer level package					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

<b>NOTICE OF ALLOWANCE MAILED</b>		Assistant Examiner	<b>CLAIMS ALLOWED</b>	
			Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		Primary Examiner	<b>DRAWING</b>	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>PREPARED FOR ISSUE</b>	Application Examiner	
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